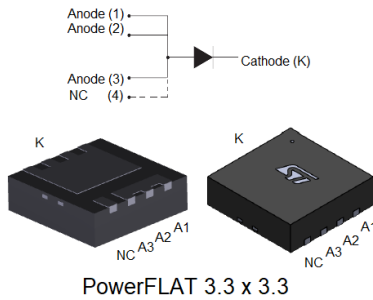


30 V, 8 A power Schottky rectifier



Features

- Very low conduction losses
- Negligible switching losses
- Extremely fast switching
- Low thermal resistance
- Avalanche capacity specified
- High junction temperature capability
- ECOPACK2 compliant

Application

- Cordless appliance
- SSD
- Battery charger
- Telecom power
- DC / DC converter
- Polarity protection
- Freewheeling

Product status link

[STPS8L30DEE](#)

Product summary

Symbol	Value
$I_{F(AV)}$	8 A
V_{RRM}	30 V
T_j (max.)	150 °C
V_F (typ.)	0.34 V

Description

This Schottky rectifier is designed for switch mode power supply and high frequency DC to DC converters.

Packaged in PowerFLAT, this device is intended for use in low voltage, high frequency, inverters, free-wheeling, by-pass diode and polarity protection applications. Its low profile was especially designed to be used in applications with space-saving constraints.

1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter		Value	Unit	
V_{RRM}	Repetitive peak reverse voltage		30	V	
$I_{F(RMS)}$	Forward rms current		15	A	
$I_{F(AV)}$	Average forward current, $\delta = 0.5$ square wave	$T_c = 130\text{ °C}$	8	A	
I_{FSM}	Surge non repetitive forward current		$t_p = 10\text{ ms}$ sinusoidal	100	A
P_{ARM}	Repetitive peak avalanche power	$t_p = 10\text{ }\mu\text{s}$	$T_c = 125\text{ °C}$	200	W
T_{stg}	Storage temperature range		-65 to +150	°C	
T_j	Maximum operating junction temperature		+150	°C	

Table 2. Thermal resistance parameters

Symbol	Parameter	Max. value	Unit
$R_{th(j-c)}$	Junction to case	4	°C/W

For more information, please refer to the following application note:

- AN5088: Rectifiers thermal management, handling and mounting recommendations

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-		1000	μA
		$T_j = 125\text{ °C}$		-	70	140	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 8\text{ A}$	-		0.50	V
		$T_j = 125\text{ °C}$		-	0.34	0.39	
		$T_j = 25\text{ °C}$	$I_F = 16\text{ A}$	-		0.57	
		$T_j = 125\text{ °C}$		-	0.44	0.51	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 0.27 \times I_{F(AV)} + 0.015 \times I_{F(RMS)}^2$$

For more information, please refer to the following application notes related to the power losses:

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses in a power diode

1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current

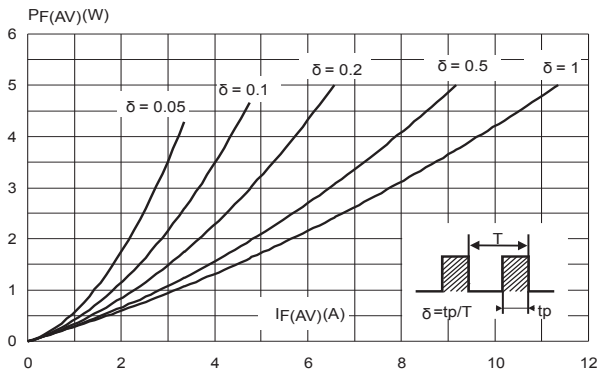


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$)

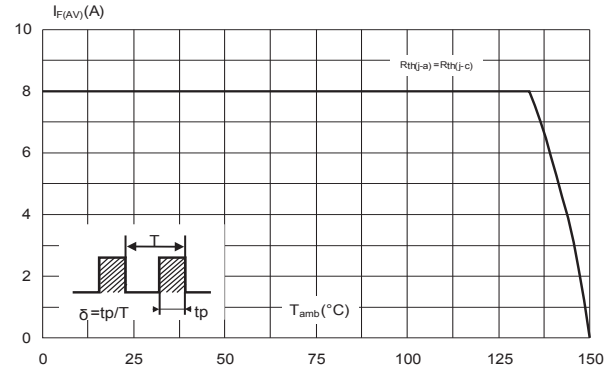


Figure 3. Normalized avalanche power derating versus pulse duration

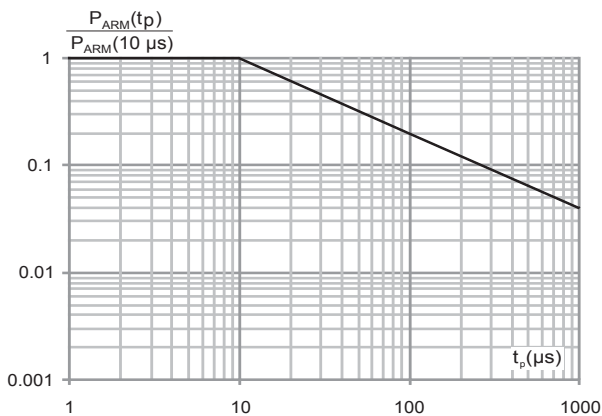


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

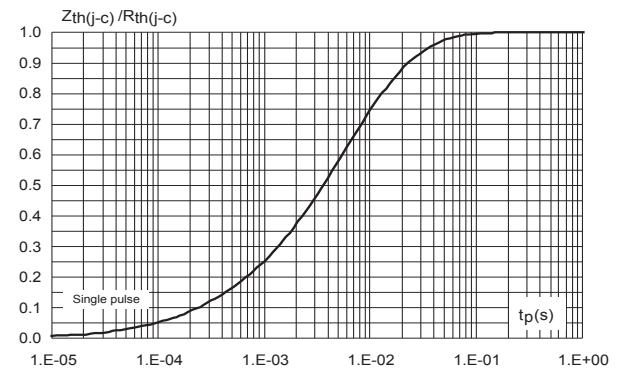


Figure 5. Reverse leakage current versus reverse voltage applied (typical values)

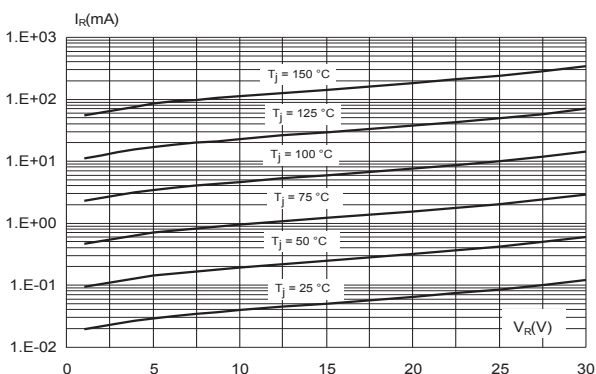


Figure 6. Junction capacitance versus reverse voltage applied (typical values)

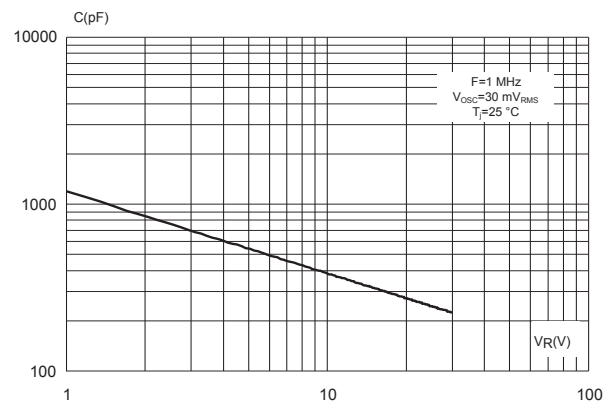


Figure 7. Forward voltage drop versus forward current

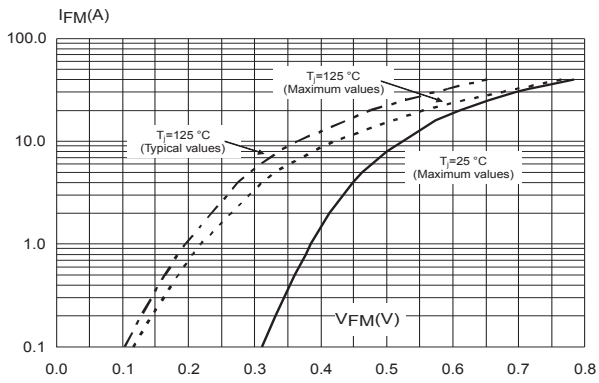
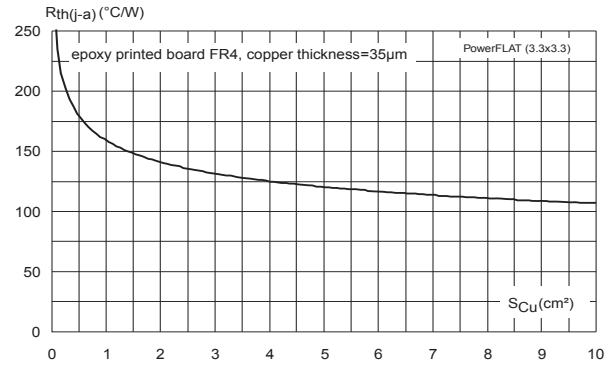


Figure 8. Thermal resistance junction to ambient versus copper surface under tab



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 PowerFLAT 3.3x3.3 mm package information

Figure 9. PowerFLAT 3.3x3.3 mm package outline

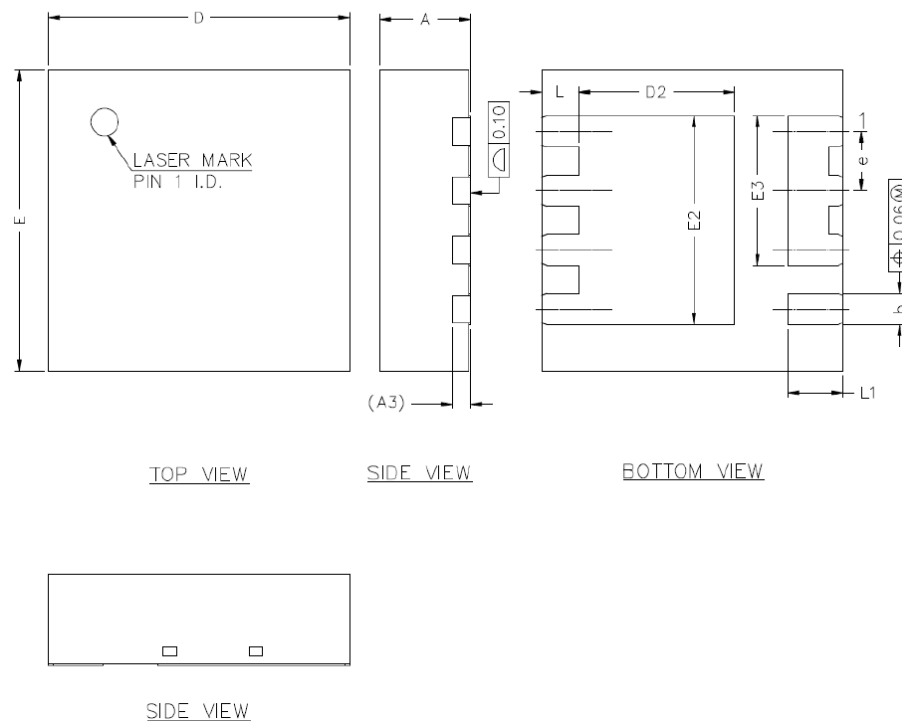
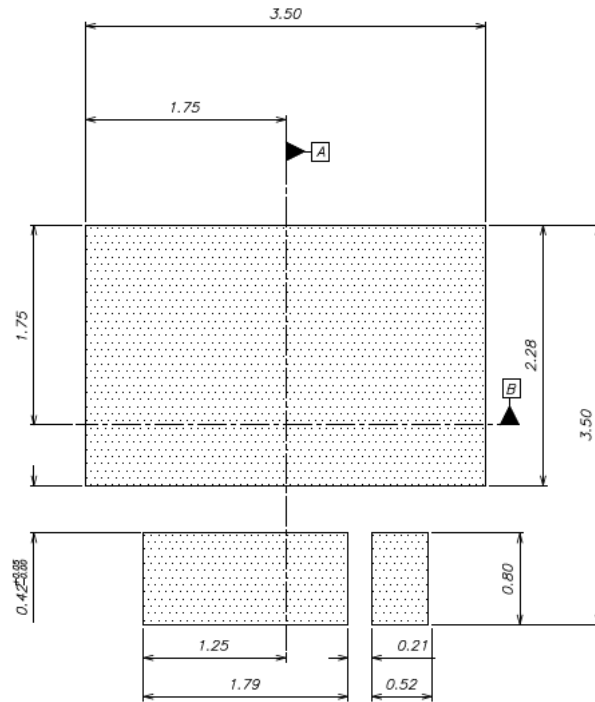


Table 4. PowerFLAT 3.3x3.3 mm mechanical data

Ref.	Dimensions		
	Millimeters		
	Min.	Typ.	Max.
A	0.90		1.10
A3		0.20	
b	0.29		0.44
D	3.20		3.40
D2	1.61		1.82
E	3.20		3.40
E2	2.19		2.39
E3	1.54		1.74
e	0.55		0.75
L	0.30		0.50
L1	0.50		0.70

Figure 10. Recommended footprint (dimensions are in mm)



3 Ordering information

Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS8L30DEE-TR	PS8L30	PowerFLAT 3.3 x 3.3	34 mg	3000	Tape and 13" reel

Revision history

Table 6. Document revision history

Date	Version	Changes
09-Sep-2012	1	First issue.
21-Apr-2022	2	Updated package outline PowerFLAT 3.3 x 3.3.

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